# Product End-of-Life Disassembly Instructions

**Product Category:** Personal Computers

**Marketing Name / Model**

[List multiple models if applicable.]

HP EliteDesk 800 G1 Small Form Factor Business PC

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**Purpose:** The document is intended for use by end-of-life recyclers or treatment facilities. It provides the basic instructions for the disassembly of HP products to remove components and materials requiring selective treatment, as defined by EU directive 2002/96/EC, Waste Electrical and Electronic Equipment (WEEE)

## 1.0 Items Requiring Selective Treatment

1.1 Items listed below are classified as requiring selective treatment.

1.2 Enter the quantity of items contained within the product which require selective treatment in the right column, as applicable.

<table>
<thead>
<tr>
<th>Item Description</th>
<th>Notes</th>
<th>Quantity of items included in product</th>
</tr>
</thead>
<tbody>
<tr>
<td>Printed Circuit Boards (PCB) or Printed Circuit Assemblies (PCA)</td>
<td>With a surface greater than 10 sq cm PCA</td>
<td>3</td>
</tr>
<tr>
<td>Batteries</td>
<td>All types including standard alkaline and lithium coin or button style batteries Yes</td>
<td>1</td>
</tr>
<tr>
<td>Mercury-containing components</td>
<td>For example, mercury in lamps, display backlights, scanner lamps, switches, batteries</td>
<td></td>
</tr>
<tr>
<td>Liquid Crystal Displays (LCD) with a surface greater than 100 sq cm</td>
<td>Includes background illuminated displays with gas discharge lamps</td>
<td></td>
</tr>
<tr>
<td>Cathode Ray Tubes (CRT)</td>
<td></td>
<td></td>
</tr>
<tr>
<td>Capacitors / condensers (Containing PCB/PCT)</td>
<td></td>
<td></td>
</tr>
<tr>
<td>Electrolytic Capacitors / Condensers measuring greater than 2.5 cm in diameter or height</td>
<td>Liteon 320W STD PSU</td>
<td>5</td>
</tr>
<tr>
<td>External electrical cables and cords</td>
<td>Yes</td>
<td>1</td>
</tr>
<tr>
<td>Gas Discharge Lamps</td>
<td></td>
<td></td>
</tr>
<tr>
<td>Plastics containing Brominated Flame Retardants weighing &gt; 25 grams (not including PCBs or PCAs already listed as a separate item above)</td>
<td></td>
<td></td>
</tr>
<tr>
<td>Components and parts containing toner and ink including liquids, semi-liquids (gel/paste) and toner chambers, and service stations.</td>
<td>Include the cartridges, print heads, tubes, vent</td>
<td></td>
</tr>
<tr>
<td>Components and waste containing asbestos</td>
<td></td>
<td></td>
</tr>
</tbody>
</table>

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PSG instructions for this template are available at EL-MF877-01
Components, parts and materials containing refractory ceramic fibers

Components, parts and materials containing radioactive substances

2.0 Tools Required

List the type and size of the tools that would typically be used to disassemble the product to a point where components and materials requiring selective treatment can be removed.

<table>
<thead>
<tr>
<th>Tool Description</th>
<th>Tool Size (if applicable)</th>
</tr>
</thead>
<tbody>
<tr>
<td>#1 Torx Screwdriver</td>
<td>T-15</td>
</tr>
<tr>
<td>#2 Phillips Screwdriver</td>
<td>2</td>
</tr>
<tr>
<td>#3 Micro shear</td>
<td>170II</td>
</tr>
<tr>
<td>Description #4</td>
<td></td>
</tr>
<tr>
<td>Description #5</td>
<td></td>
</tr>
</tbody>
</table>

3.0 Product Disassembly Process

3.1 List the basic steps that should typically be followed to remove components and materials requiring selective treatment:

1. Remove the access panel. (see Figure 1 below)
2. Disconnect the cables from the board. (see Figure 2-7 below)
3. Remove the HDD, slim ODD, ODD from cage. (see Figure 8-10 below)
4. Remove the Memory from the board. (see Figure 11 below)
5. Remove the CPU HeatSink from the board. (see Figure 12&13 below)
6. Remove the fan from CPU HeatSink. (see Figure 14&15 below)
7. Remove the CPU from the board. (see Figure 16&17 below)
8. Remove the battery from the system board. (see Figure 18 below)
9. Remove stone card from chassis. (see Figure 19&20 below)
10. Remove M/B from chassis. (see Figure 21&22 below)
11. Remove system fan from chassis. (see Figure 23&24 below)
12. Remove PSU from chassis. (see Figure 25-27 below)
13. Remove Speaker from chassis. (see Figure 28&29 below)
14. Remove front bezel. (see Figure 30 below)
15. Remove Front I/O and power LED cable. (see Figure 31-33 below)
16. Remove PSU cover. (see Figure 34&35 below)
17. Remove PSU PCA, and disconnect power cables. (see Figure 36&37 below)
18. Remove the Electrolytic Capacitors. (see Figure 38-40 below)

3.2 Optional Graphic. If the disassembly process is complex, insert a graphic illustration below to identify the items contained in the product that require selective treatment (with descriptions and arrows identifying locations).
<table>
<thead>
<tr>
<th>Figure</th>
<th>Description</th>
</tr>
</thead>
<tbody>
<tr>
<td>Figure 1</td>
<td>Remove the Access Panel</td>
</tr>
<tr>
<td>Figure 2</td>
<td>Disconnect PSU cables from the board</td>
</tr>
<tr>
<td>Figure 3</td>
<td>Disconnect the ODD/HDD PSU cables</td>
</tr>
<tr>
<td>Figure 4</td>
<td>Disconnect the slim ODD cables</td>
</tr>
<tr>
<td>Figure 5</td>
<td>Disconnect the cables from the HDD</td>
</tr>
<tr>
<td>Figure 6</td>
<td>Disconnect the CPU HeatSink cable</td>
</tr>
</tbody>
</table>

PSG instructions for this template are available at [EL-MF877-01](#)
Figure 7: Disconnect the Front IO cable

Figure 8: Remove the HDD from cage

Figure 9: Remove the slim ODD from cage

Figure 10: Remove the ODD from cage

Figure 11: Remove the Memory from the board

Figure 12: Loose the screws from the CPU HeatSink

PSG instructions for this template are available at [EL-MF877-01](#).
Figure 13 Remove the CPU HeatSink from the board

Figure 14 Loose the screws from the CPU HeatSink

Figure 15 Remove the fan from CPU HeatSink

Figure 16 Rotate the handle and open it up

Figure 17 Remove the CPU from the board

Figure 18 Remove the battery from the system board

PSG instructions for this template are available at EL-MF877-01
Figure 19: Loose the stone card screws
Figure 20: Remove the stone card from MB

Figure 21: Loose the screws from board
Figure 22: Remove M/B from chassis

Figure 23: Loose the screws from system fan
Figure 24: Remove system fan

PSG instructions for this template are available at [EL-MF877-01](#)
Figure 25: Loose the screws from PSU

Figure 26: Press the baffle and slide the PSU

Figure 27: Remove PSU from chassis

Figure 28: Loose the screws from Speaker

Figure 29: Remove Speaker

Figure 30: Remove front bezel

PSG instructions for this template are available at [EL-MF877-01](#)
Figure 31: Loose the screw of Front IO

Figure 32: Remove Front IO cable

Figure 33: Remove power LED cable

Figure 34: Remove the screws on the PSU chassis

Figure 35: Lift the cover off the power supply

Figure 36: Cut the cable tie

PSG instructions for this template are available at EL-MF877-01
Figure 37 Remove PSU MB from PSU Chassis (Liteon 320W STD)

Figure 38 Show Ele-Cap on PCBA

Figure 39 Remove Ele-Cap from PCBA

Figure 40 Remove Ele-Cap from PCBA

PSG instructions for this template are available at EL-MF877-01